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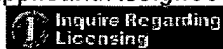
Title: **JP2000319793A2: FUNCTIONAL ALLOY PLATING OF JOINING MATERIAL INSTEAD OF Pb AND ELECTRONIC PARTS MATERIAL FOR PACKING APPLIED WITH THE FUNCTIONAL ALLOY PLATING**

Country: **JP Japan**

Kind: **A2 Document Laid open to Public inspection**

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Issued/Filed Dates: **Nov. 21, 2000 / May 7, 1999**

Application Number: **JP1999000164307**

IPC Class: **C25D 3/30; C22C 13/00; C22C 13/02; H01L 23/50;**

Priority Number(s): **May 7, 1999 JP1999000164307**

Abstract: **Problem to be solved:** To remarkably improve the functions of the existing functional alloy plating of a joining material for packing with a joining material instead of solder (tin-lead alloy) by using a special waveform plating method, to remove harmful plating from various electronic parts used for electronic apparatus and to allow the same to be useful for environmental protection.



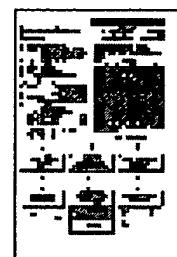
**Solution:** In the functional alloy plating of a joining material instead of Pb, Sn (tin) is used as a base, one kind is selected from Bi (bismuth), Ag (silver) and Cu (copper), the content of Bi to the above Sn is set to  $\leq 1.0\%$ , the content of Bi to Sn to 2.0 to 10.0%, the content of Ag to Sn to 1.0 to 3.0%, 3.0 to 5.0%, or 8.0 to 10.0%, and the content of Cu to Sn to 0.5 to 1.0%, and electrolytic treatment by a special waveform is applied. Moreover, the electronic parts material for packing is obtd. by applying the functional alloy plating.

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Family: [Show known family members](#)

Other Abstract Info: **CHEMABS 133(26)368557N CHEMABS 133(26)368557N  
DERABS C2001-128465 DERABS C2001-128465**

Foreign References: **No patents reference this one**



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